Board Characteristics

1. All dimensions in mm, unless specified
2. Minimum trace width: 8 mils
3. 1 Oz Copper on all power and signal layers
4. Silkscreen on both sides
5. PCB Thickness: 2.36mm
6. Soft Au finish (ENIG)
7. Via Fill and Overplate. Vias in Pad must be filled with Peters PP-2795 or equivalent solid fills.
8. Material FR 4 with Tg > 180°C
9. All 8 mil stripline traces shall be Zc=500mm